

IGBT

SGW10N60RUFD

Short Circuit Rated IGBT

General Description

Fairchild's RUFD series of Insulated Gate Bipolar Transistors (IGBTs) provide low conduction and switching losses as well as short circuit ruggedness. The RUFD series is designed for applications such as motor control, uninterrupted power supplies (UPS) and general inverters where short circuit ruggedness is a required feature.

Features

- Short circuit rated 10us @ $T_C = 100$ °C, $V_{GE} = 15$ V
- · High speed switching
- Low saturation voltage : $V_{CE(sat)} = 2.2 \text{ V} @ I_C = 10 \text{A}$
- High input impedance
- CO-PAK, IGBT with FRD : $t_{rr} = 42$ ns (typ.)

Applications

AC & DC motor controls, general purpose inverters, robotics, and servo controls.





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Description		SGW10N60RUFD	Units	
V _{CES}	Collector-Emitter Voltage		600	V	
V _{GES}	Gate-Emitter Voltage		± 20	V	
	Collector Current	@ T _C = 25°C	16	А	
I _C	Collector Current	@ T _C = 100°C	10	Α	
I _{CM (1)}	Pulsed Collector Current		30	Α	
I _F	Diode Continuous Forward Current	@ T _C = 100°C	12	А	
I _{FM}	Diode Maximum Forward Current		92	Α	
T _{SC}	Short Circuit Withstand Time	@ T _C = 100°C	10	us	
P _D	Maximum Power Dissipation	@ T _C = 25°C	75	W	
	Maximum Power Dissipation	@ T _C = 100°C	30	W	
T _J	Operating Junction Temperature		-55 to +150	°C	
T _{stg}	Storage Temperature Range		-55 to +150	°C	
T _L	Maximum Lead Temp. for Soldering Purposes, 1/8" from Case for 5 Second	ds	300	°C	

(1) Repetitive rating : Pulse width limited by max. junction temperature

Thermal Characteristics

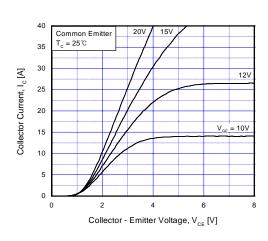
Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction-to-Case		1.6	°C/W
$R_{\theta JC}(DIODE)$	Thermal Resistance, Junction-to-Case		2.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (PCB Mount) (2)		40	°C/W

Notes:
(2) Mounted on 1" squre PCB (FR4 or G-10 Material)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Cha	racteristics					
BV _{CES}	Collector-Emitter Breakdown Voltage	$V_{GE} = 0V, I_{C} = 250uA$	600			V
$\Delta B_{VCES}/$ ΔT_J	Temperature Coefficient of Breakdown Voltage	V _{GE} = 0V, I _C = 1mA		0.6		V/°C
I _{CES}	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$			250	uA
I _{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$			± 100	nA
	acteristics					
V _{GE(th)}	G-E Threshold Voltage	$I_C = 10$ mA, $V_{CE} = V_{GE}$	5.0	6.0	8.5	V
	Collector to Emitter	$I_C = 10A$, $V_{GE} = 15V$		2.2	2.8	V
V _{CE(sat)}	Saturation Voltage	I _C = 16A, V _{GE} = 15V		2.5		V
-	Characteristics					
C _{ies}	Input Capacitance	$V_{CE} = 30V_{V_{GE}} = 0V_{V_{CE}}$		660		pF
C _{oes}	Output Capacitance	f = 1MHz		115		pF
C _{res}	Reverse Transfer Capacitance	1 – 1111112		25		pF
t _{d(on)}	Turn-On Delay Time			15		ns
t _r	Rise Time			30		ns
t _{d(off)}	Turn-Off Delay Time	$V_{CC} = 300 \text{ V}, I_{C} = 10\text{A},$		36	50	ns
t _f	Fall Time	$R_G = 20\Omega, V_{GE} = 15V,$		158	200	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 25°C		141		uJ
E _{off}	Turn-Off Switching Loss			215		uJ
E _{ts}	Total Switching Loss			356	500	uJ
t _{d(on)}	Turn-On Delay Time			16		ns
t _r	Rise Time			33		ns
t _{d(off)}	Turn-Off Delay Time	$V_{CC} = 300 \text{ V}, I_{C} = 10\text{A},$		42	60	ns
t _f	Fall Time	$R_G = 20\Omega, V_{GE} = 15V,$		242	350	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 125°C		161		uJ
E _{off}	Turn-Off Switching Loss	1		452		uJ
E _{ts}	Total Switching Loss	1		613	860	uJ
T _{sc}	Short Circuit Withstand Time	V _{CC} = 300 V, V _{GE} = 15V @ T _C = 100°C	10			us
Q _g	Total Gate Charge			30	45	nC
Q _{ge}	Gate-Emitter Charge	$V_{CE} = 300 \text{ V}, I_{C} = 10\text{A},$		5	10	nC
Q _{gc}	Gate-Collector Charge	V _{GE} = 15V		8	16	nC
	Internal Emitter Inductance	Measured 5mm from PKG		7.5		nH

Electrical Characteristics of DIODE $T_C = 25^{\circ}C$ unless otherwise noted

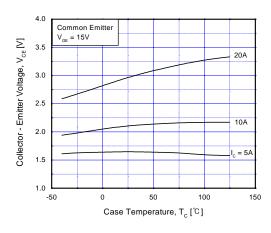
Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Units
	Diode Forward Voltage	I _F = 12A	$T_C = 25^{\circ}C$		1.4	1.7	V
V_{FM}			T _C = 100°C		1.3		
	Diode Reverse Recovery Time		$T_C = 25^{\circ}C$		42	60	ns
^L rr			T _C = 100°C		60		
	Diode Peak Reverse Recovery	I _F = 12A, di/dt = 200A/us	$T_C = 25^{\circ}C$		3.5	6.0	Α
^I rr	Current		T _C = 100°C		5.6		_ A
Q _{rr}	Diode Reverse Recovery Charge		$T_C = 25^{\circ}C$		80	180	nC
			$T_C = 100^{\circ}C$		220		110



Common Emitter

Fig 1. Typical Output Characteristics

Fig 2. Typical Saturation Voltage Characteristics



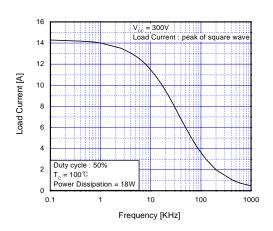
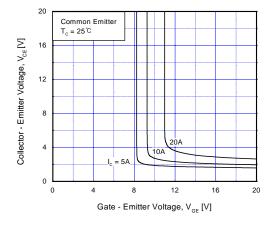


Fig 3. Saturation Voltage vs. Case Temperature at Variant Current Level

Fig 4. Load Current vs. Frequency



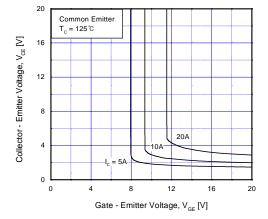


Fig 5. Saturation Voltage vs. V_{GE}

Fig 6. Saturation Voltage vs. V_{GE}

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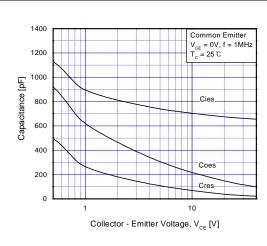


Fig 7. Capacitance Characteristics

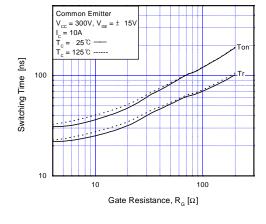


Fig 8. Turn-On Characteristics vs.
Gate Resistance

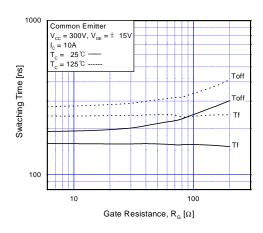


Fig 9. Turn-Off Characteristics vs.
Gate Resistance

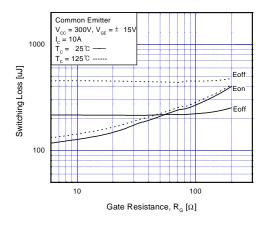


Fig 10. Switching Loss vs. Gate Resistance

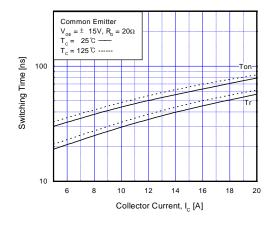


Fig 11. Turn-On Characteristics vs. Collector Current

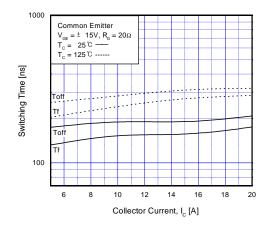
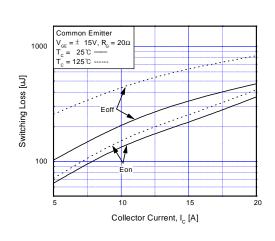


Fig 12. Turn-Off Characteristics vs. Collector Current



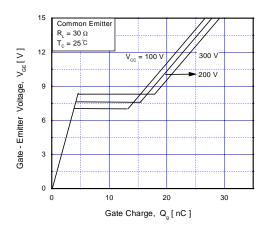
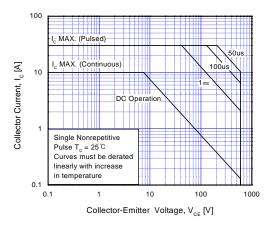


Fig 13. Switching Loss vs. Collector Current

Fig 14. Gate Charge Characteristics



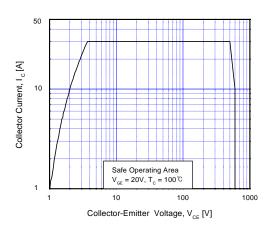


Fig 15. SOA Characteristics

Fig 16. Turn-Off SOA Characteristics

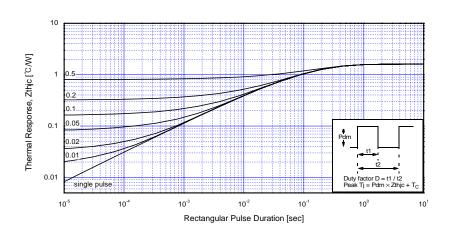
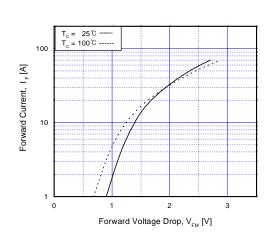


Fig 17. Transient Thermal Impedance of IGBT



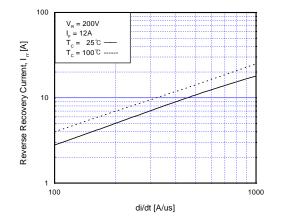
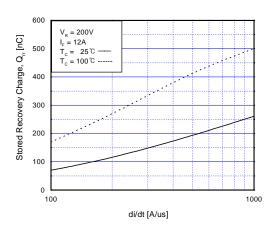


Fig 18. Forward Characteristics

Fig 19. Reverse Recovery Current



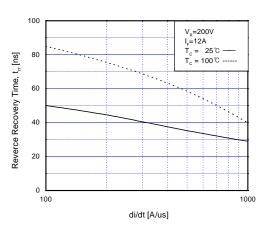
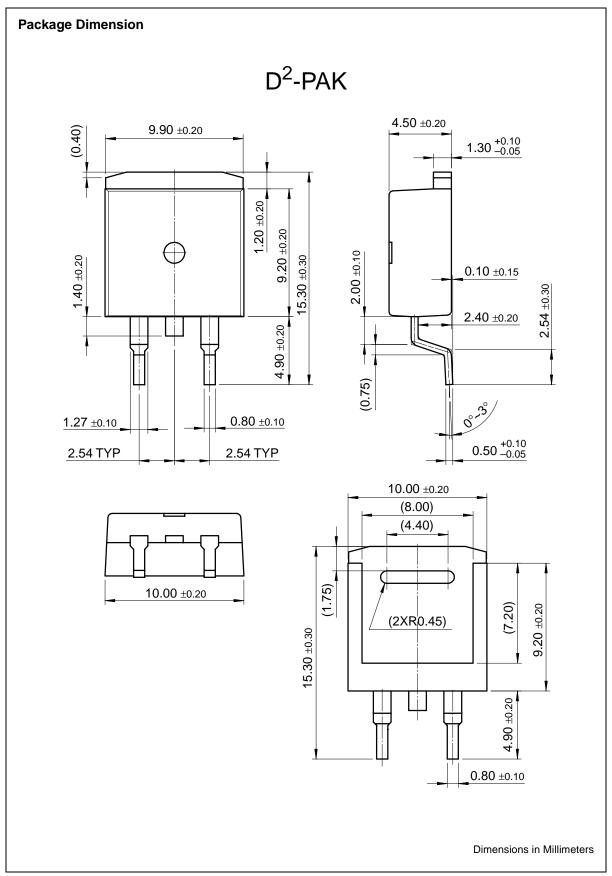


Fig 20. Stored Charge

Fig 21. Reverse Recovery Time



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Product status/pricing/packaging

Product	Product status	Pricing*	Package type	Leads	Packing method
SGW10N60RUFDTM	Full Production	\$1.48	TO-263(D2PAK)	2	TAPE REEL

^{* 1,000} piece Budgetary Pricing

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